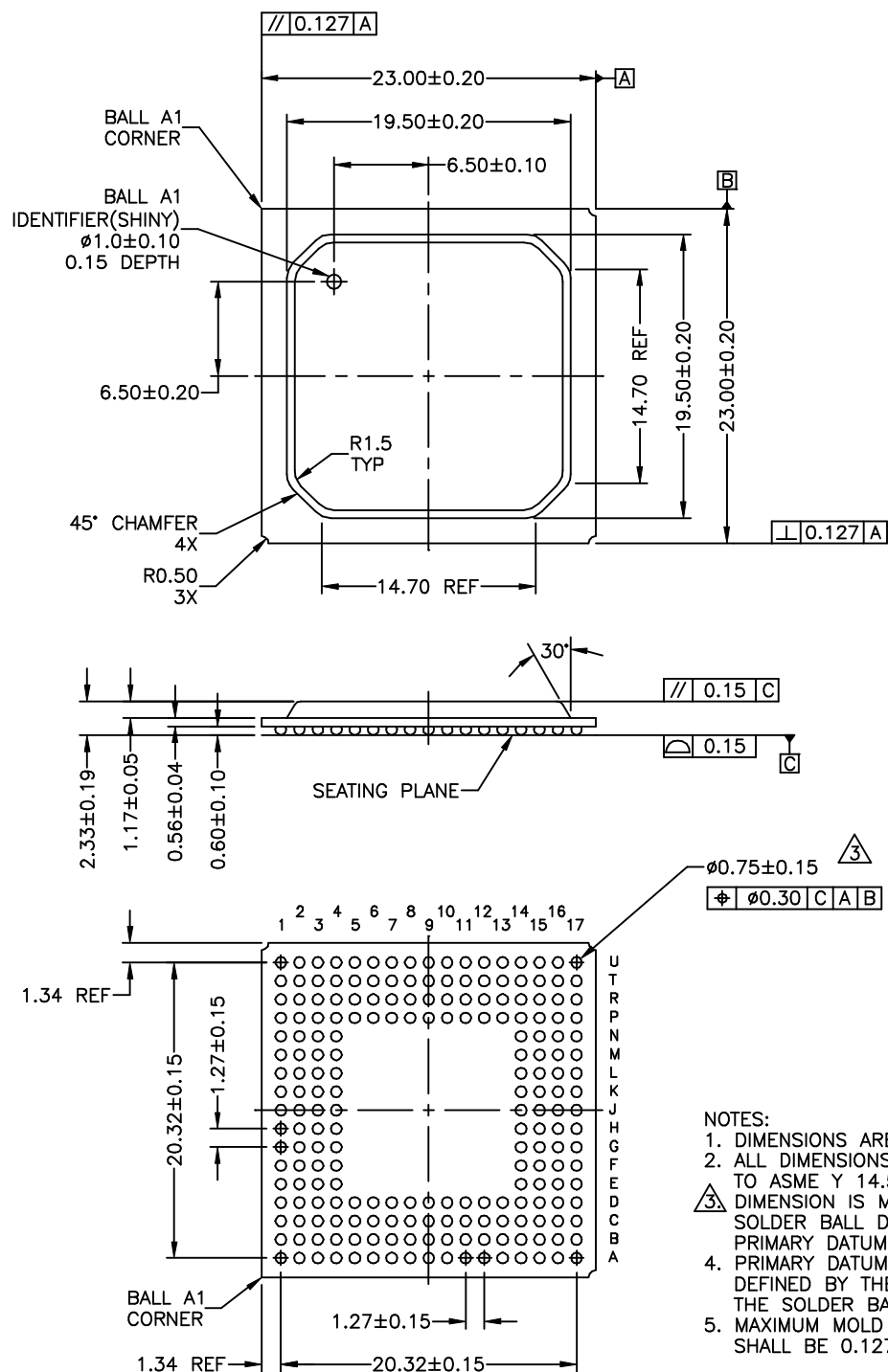




NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. ALL DIMENSIONS AND TOLERANCE CONFORM TO ASME Y 14.5M-1994.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. MAXIMUM MOLD TO SUBSTRATE OFFSET SHALL BE 0.127.

SIGNATURE		DATE		 Dallas Semiconductor			
DOC. CONTROL:							
ENGR. MGR:				MARKETING OUTLINE – 208 PBGA 23 X 23, 2.33 THICK, 4 LAYER			
MFG. ENGR:							
CHECKED BY:							
DRAWN BY:				SIZE	FSCM NO	PART NO.	REV
				A			A
DO NOT SCALE DWG.				SCALE 2/1		SHEET 1 OF 1	